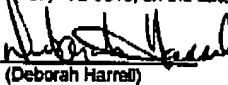


I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office, facsimile no. (703) 872-9318, on the date shown below.

Dated: 7/7/03

Signature: 
(Deborah Harrel)

Docket No.: YOR91990336US2
(20140-00300-US)
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chao-Kun Hu

Conf. No. 8304

Application No.: 10/054,605

Group Art Unit: 2815

Filed: November 13, 2001

Examiner: Paul E. Brock, II

For: REDUCED ELECTROMIGRATION AND
STRESS INDUCED MIGRATION OF COPPER
WIRES BY SURFACE COATING

RESPONSE AFTER FINAL UNDER 37 CFR 1.116

M/S AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action dated March 4, 2003 (Paper No. 8), please amend the above-identified U.S. patent application as follows:

SUMMARY OF AMENDMENTS**CLAIMS**

07/17/2003 AJOHNSD1 00000003 220185 10054605

01 FC:1251

110.00 DA

There are no amendments to the claims.

A complete listing of all claims ever present in this case in ascending order with status identifier is presented in a separate section.

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